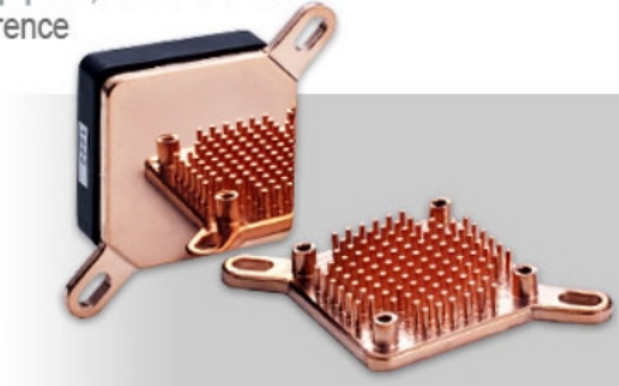


BGA Cooler



SLF-30(mm)

Pure Copper, Low Profile
Less Interference



SPECIFICATION

COOLER

Total dimension	32x32x13.5(H)mm
Weight	39g
Rth	2.25 °C/W

HEATSINK

Material	CU 1100
Technology	Forge
Dimension	32*32*6.6(h)mm
Base (thickness)	2.6 mm
Weight	31.5 g.
Finish	Redox

FAN

Dimension	30*30*6.5(H)mm.
Bearing	Hypro
Voltage	12 V.DC
Current	0.064 Amp
Speed	10500 R.P.M.
Air flow	3.5 CFM

Heat source

Dimension	12*12 mm
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